



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hiroshi Sakai, et al.

Examiner: Kevin L. McHenry

Serial No.: 10/063,915

Art Unit: 1725

Filed: May 23, 2002

Docket: 15574

For: SOLDER PASTE PRINTING METHOD
AND APPARATUS FOR PRINTING
SOLDER PASTE ON A BOARD ON
WHICH WIRING PATTERNS ARE FORMED

Dated: February 3, 2005

Conf. No.: 4405

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

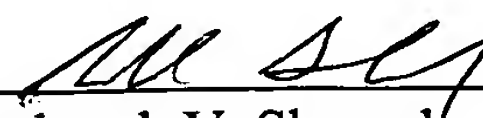
In accordance with 37 C.F.R §§1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

1. European Patent Application Publication No. EP 0 859 540 A1, dated August 19, 1998;
2. Vincent, J.H., et al., "Lead-Free Solders for Electronic Assembly", The GEC Journal of Research (1994), Vol. 11, No. 2, pp. 76-89;

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop 313(c), Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 3, 2005.

Dated: February 3, 2005


Aasheesh V. Shravan

3. Steen, H., "Assessing Lead-Free Solders for Electronics", Electronic Packaging & Production (1994), Vol. 34, No. 12, pp. 32-34, 36;
4. United States Patent No. 5,346,118, issued to Degani et al., dated September 13, 1994;
5. European Patent Application Publication No. EP 0 848 586 A1, dated June 17, 1998; and
6. European Patent Application Publication No. EP 0 867 255 A2, dated September 30, 1998.

The references were cited in a Search Report dated December 8, 2004 received from the European Patent Office. Applicants are submitting copies of the above-cited references, together with a copy of the Search Report. The relevance of the above-identified references has been described in the Search Report.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. § 1.97(b), no statement or fee is required.

Respectfully submitted,



Aasheesh V. Shravah
Registration No. 54,445

Scully, Scott, Murphy & Presser
400 Garden City Plaza - Ste. 300
Garden City, New York 11530
(516) 742-4343

PJE:AVS:jam

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				Docket Number (Optional) 15574		Application Number 10/063,915	
				Applicant(s) Hiroshi Sakai, et al.			
				Filing Date May 23, 2002		Group Art Unit 1725	

O I P E
 FEB 07 2005
 PATENT & TRADEMARK OFFICE

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		5,346,118	9/13/1994	Degani et al.			

FOREIGN PATENT DOCUMENTS								
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		EP 0 859 540 A1	8/19/1998	EPO				
		EP 0 848 586 A1	6/17/1998	EPO				
		EP 0 867 255 A2	9/30/1998	EPO				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)		
		Vincent, J.H., et al., "Lead-Free Solders for Electronic Assembly", The GEC Journal of Research (1994), Vol. 11, No. 2, pp. 76-89
		Steen, H., "Assessing Lead-Free Solders for Electronics", Electronic Packaging & Production (1994), Vol. 34, No. 12, pp. 32-34, 36

EXAMINER	DATE CONSIDERED
----------	-----------------

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.